

TSG-RAN Working Group 1 meeting #10
Beijing, China, January 18-21 2000

TSGR1#10(00)0094

Agenda Item: 9
Source: CWTS
To: TSG RAN WG1
Title: WG1 Work plan for low chip rate TDD option
Document for: Discussion and approval

Work Task Description

Title

Physical layer of low chip rate TDD option

Intended Output

Modification of the specifications concerning the low chip rate TDD option.

TS	25.201	Physical layer – General description
TS	25.221	Physical channels and mapping of transport channels onto physical channels (TDD)
TS	25.222	Multiplexing and channel coding (TDD)
TS	25.223	Spreading and modulation (TDD)
TS	25.224	TDD; physical layer procedures
TS	25.225	Physical layer; measurements

* To ease the description and/or the clarification, some new specifications for low chip rate option may be created.

Impact on Other Technical Specifications and Technical Reports

The other expect impact on technical specifications will be for:

TS	25.301	Radio Interface Protocol Architecture
TS	25.302	Services provided by the physical layer
TS	25.303	UE functions and inter-layer procedures in connected mode
TS	25.304	UE procedure in Idle mode
TS	25.305	Location services (LCS) features
TS	25.321	Medium Access Control (MAC) Protocol Specification
TS	25.322	Radio Link Control (RLC) Protocol Specification
TS	25.331	Radio Resource Control (RRC) Protocol Specification
TS	25.402	Synchronisation in UTRAN Stage 2

Technical Scope

In Release 2000 work plan, the integration of the low chip rate TDD option is included. The integration work will enable the low chip rate TDD mode with its specific properties. And this work will affect the specifications for physical layer, higher layers and also the RF specifications as well.

The purpose of this new work task is to confirm the tasks to be done in physical layer group (working group 1) for low chip rate option for Release 2000.

The features and properties related involved in physical layer of low chip rate option will be:

- The frame structure and the burst structure
- Channel description and mapping
- Modulation and spreading
- Channel coding and multiplexing
- Physical layer procedures
- Measurements by physical layer

Other properties and features involved for higher layers and RF will be described in the working plan for other working group.

Impact on Other 3GPP features

none

Schedule of Tasks to be Performed.

Task	Planned Start	Planned Finish
Work task Creation	10/01/2000	
Work Task approval	18/01/2000	
Drafting and discussion	01/2000	09/2000
Submission to TSG RAN for approval		

Note: * These dates are a estimation at present

Supporting Individual Members

Rapporteur